Jinuk Byun

List of Publications by Year
in descending order

20 papers	441 citations	933447 10 h-index	794594 19 g-index
20 all docs	20 docs citations	20 times ranked	654 citing authors

#	Article	IF	Citations
1	Electrodeposited Ni dendrites with high activity and durability for hydrogen evolution reaction in alkaline water electrolysis. Journal of Materials Chemistry, 2012, 22, 15153.	6.7	159
2	Ethylenediamine Promotes Cu Nanowire Growth by Inhibiting Oxidation of Cu(111). Journal of the American Chemical Society, 2017, 139, 277-284.	13.7	69
3	Impact of Surface Hydrophilicity on Electrochemical Water Splitting. ACS Applied Materials & Interfaces, 2021, 13, 11940-11947.	8.0	65
4	Largeâ€Scale Synthesis of Water Dispersible Ceria Nanocrystals by a Simple Solâ€“Gel Process and Their Use as a Chemical Mechanical Planarization Slurry. European Journal of Inorganic Chemistry, 2008, 2008, 855-858.	2.0	23
5	Catalytic growth of a colloidal carbon sphere by hydrothermal reaction with iron oxide (Fe3O4) catalyst. Materials Letters, 2014, 125, 213-217.	2.6	17
6	Investigation of cleaning solution composed of citric acid and 5-aminotetrazole. Korean Journal of Chemical Engineering, 2011, 28, 1619-1624.	2.7	13
7	Acidâ€durable, highâ€performance cobalt phosphide catalysts for hydrogen evolution in proton exchange membrane water electrolysis. International Journal of Energy Research, 2021, 45, 16842-16855.	4.5	12
8	Conformal Cu Seed Layer Formation by Electroless Deposition in Non-Bosch through Silicon Vias. Electrochemical and Solid-State Letters, 2012, 15, D26.	2.2	11
9	High Accuracy Concentration Analysis of Accelerator Components in Acidic Cu Superfilling Bath. Journal of the Electrochemical Society, 2016, 163, D33-D39.	2.9	11
10	High strength Cu foil without self-annealing prepared by 2M5S-PEG-SPS. Korean Journal of Chemical Engineering, 2019, 36, 981-987.	2.7	11
11	Thin film silver deposition by electroplating for ULSI interconnect applications. Korean Journal of Chemical Engineering, 2009, 26, 265-268.	2.7	10
12	Evaluation of Stability and Reactivity of Cu Electroless Deposition Solution by In-Situ Transmittance Measurement. Journal of the Electrochemical Society, 2011, 158, D541.	2.9	9
13	Systematic Approach to Designing a Highly Efficient Coreâ€“Shell Electrocatalyst for N₂O Reduction. ACS Catalysis, 2021, 11, 15089-15097.	11.2	9
14	Pdâ€“Cu alloy catalyst synthesized by citric acid-assisted galvanic displacement reaction for N2O reduction. Journal of Applied Electrochemistry, 2020, 50, 395-405.	2.9	6
15	Optimization of Solution Condition for an Effective Electrochemical Reduction of N2O. Electroanalysis, 2019, 31, 739-745.	2.9	4
16	Octylphenol ethoxylate surfactant as a suppressor in copper electrodeposition. Transactions of the Institute of Metal Finishing, 2019, 97, 22-27.	1.3	4
17	Real-Time Observation of Cu Electroless Deposition: Effect of EDTA on Removing of Cu Oxide and Adsorption of Formaldehyde. Journal of the Electrochemical Society, 2013, 160, D3134-D3138.	2.9	3
18	Gravimetric analysis of the autocatalytic growth of copper microparticles in aqueous solution. RSC Advances, 2019, 9, 37895-37900.	3.6	3

#	Article	IF	Citations
19	Cu seed layer damage caused by insoluble anode in Cu electrodeposition. Korean Journal of Chemical Engineering, 2017, 34, 1490-1494.	2.7	2
20	Sawtoothâ€•or Pyramidalâ€patterned Si Negative Electrode Fabricated by Microâ€Electroâ€Mechanical Systems for Liâ€•ion Secondary Battery. Bulletin of the Korean Chemical Society, 2016, 37, 1747-1753.	1.9	0